

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.  
 Contact: Copper Alloy  
 Shell: STAINLESS

PLATING:

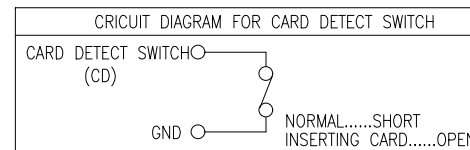
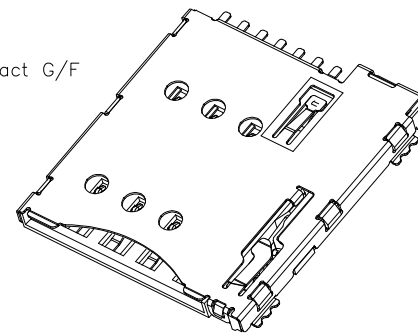
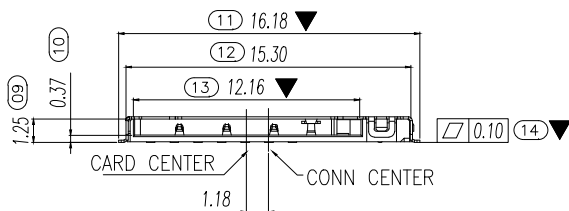
Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F  
 Shell: Plated 30u" Ni Overall  
 Plated G/F Selective Contact Area

Electrical:

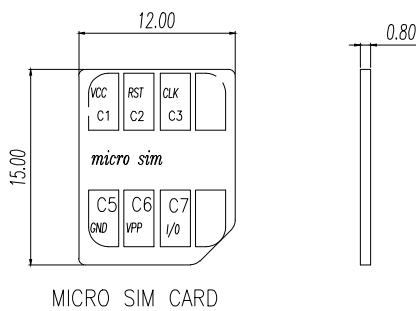
Current Rating :0.5A.  
 Voltage Rating :30V DC.  
 Ambient Temperature Range :-40°C~+85°C  
 Storage Temperature Range :-40°C~+85°C  
 Ambient Humidity Range :95% R.H. Max.  
 Contact Resistance:100mΩ max.  
 Insulation Resistance:1000MΩ min./500V DC  
 Dielectric Withstanding Voltage:500V AC  
 Mating Cycles:5,000 Insertions  
 Temperature:260°C ±5'  
 Salt spray time:24H

■ CIRCUT TRACE KEEP OUT AREA  
 ■ SMT SOLDER AREA  
 THERE SHOULD NOT BE ANY CIRCUITRIES  
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05

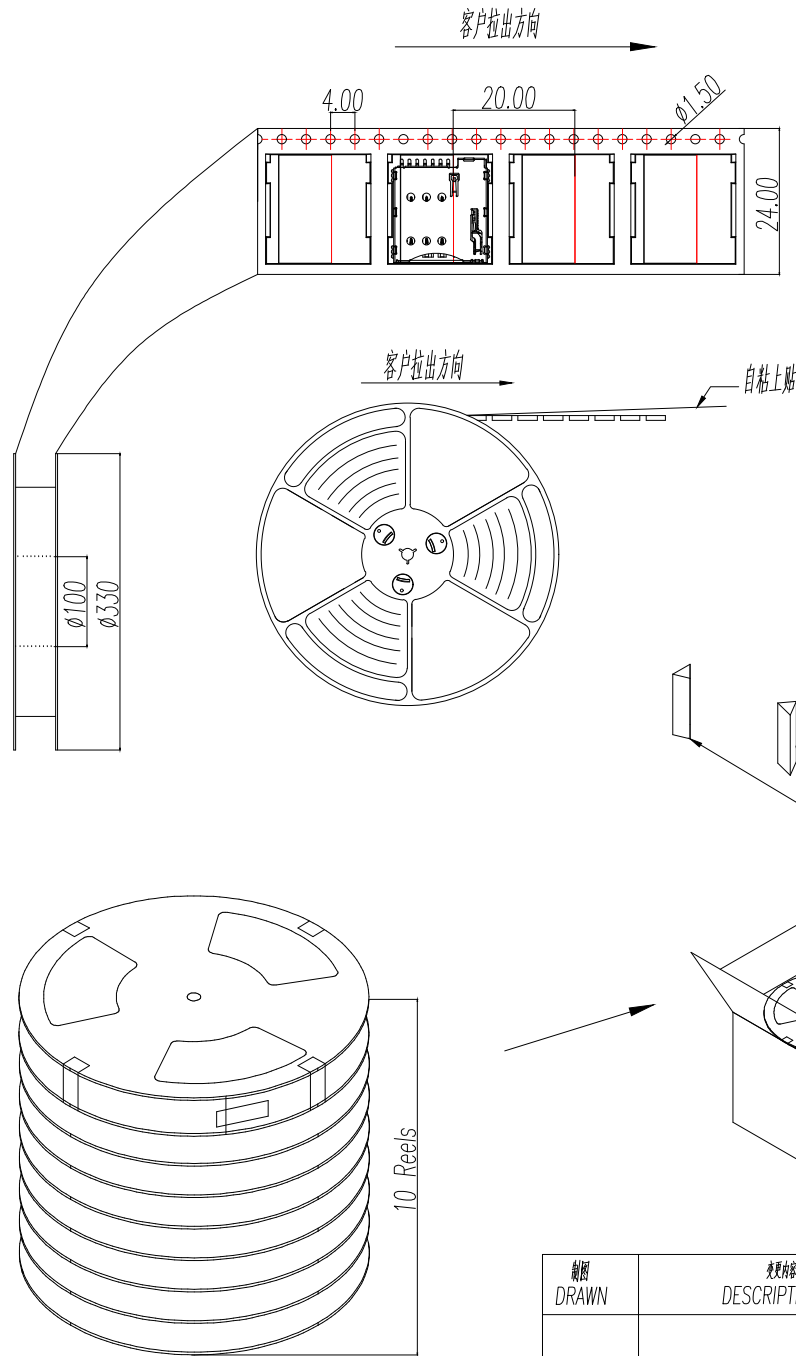


MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A
CD	DETECTION SWITCH



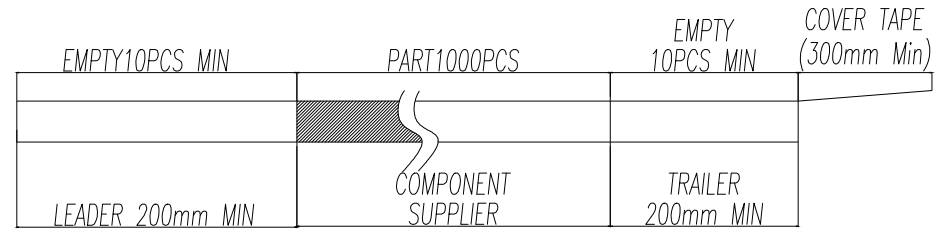
制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA	料号 PART NO.	BX-SIM-1.35H7PJ-Z	版本 REV.	A
			X±0.50	X'±2"						
			.X±0.30	.X'±1"	审核 CHECK	EVA	品名 TITLE	H1.35 7PIN MICRO SIM CARD PUSH PUSH	页次 SHEET	1/1
			.XX±0.20	.XX'±0.5"	批准 APPROVAL	JADE	客户料号 CUTM.NO.			
					单位 UNITS	MM	比例 SCALE	1:1		



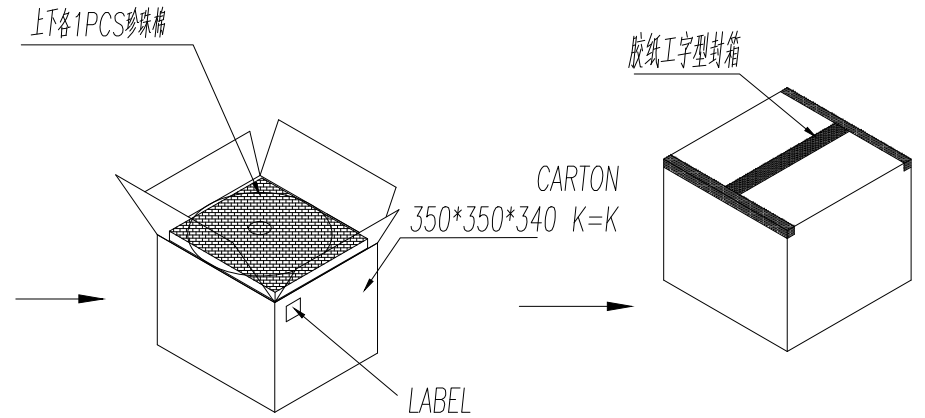


NOTES

1. NUMBER OF CONNECTORS:1000PCS/REEL
2. LEAD TAPE LENGTH



3. QUANTITY:10000PCS/CARTON



制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA	料号 PART NO.	BX-SIM-1.35H7PJ-Z	版本 REV.	A
			X.±0.50	X.*±2°	审核 CHECK	EVA	品名 TITLE	H1.35 7PIN MICRO SIM CARD PUSH PUSH 键	页次 SHEET	1/1
			.X±0.30	.X*±1°	批准 APPROVAL	JADE	客户料号 CUTM.NO.			
			.XX±0.20	.XX*±0.5°	单位 UNITS	MM	比例 SCALE	1:1	<b>Bossie (博锡)</b>	